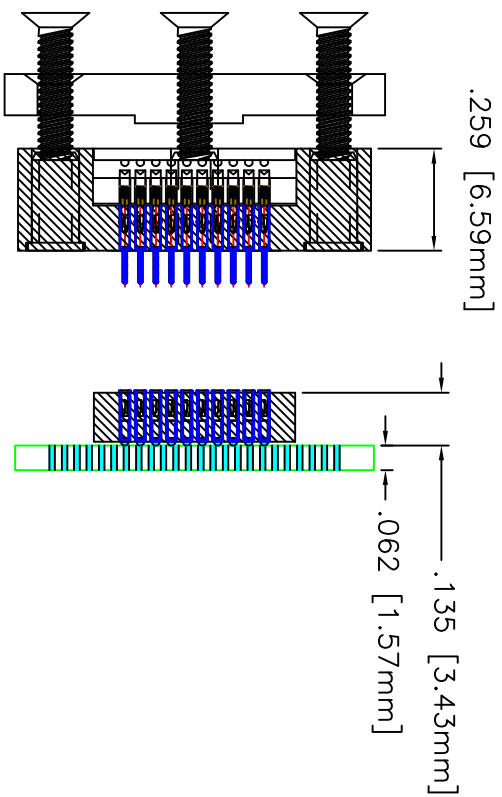
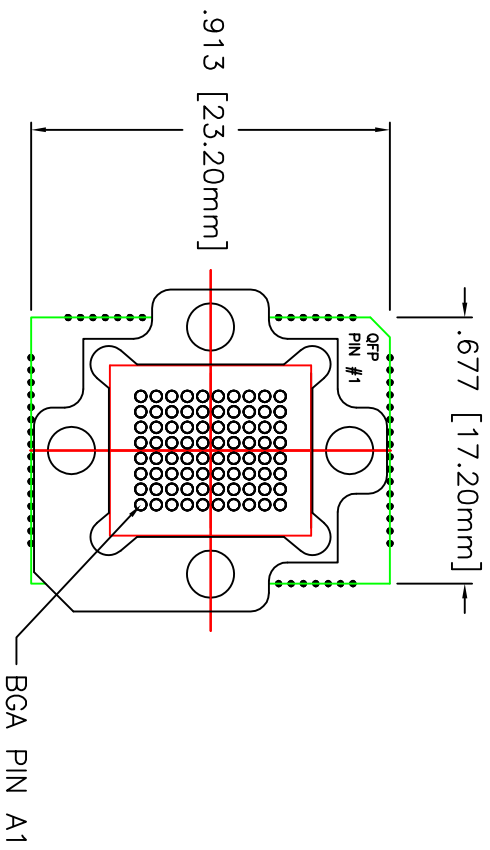


MATERIAL SPECIFICATIONS:
 STANDARD MATERIAL:
 GLASS EPOXY FR-4, IPC-4101/24,
 MIL-S-13949/04-QF/GF/L,
 94V-0, CONTINUOUS USE TEMP 150C,
 HEAT DEFLECTION TEMP@254 PSI/175C

REVISIONS		DESCRIPTION	DATE	APPROVED
---	A	NEW RELEASE	11/07/07	

TOP VIEW



NOTES:
 FBS08051006F SOLDERS TO TOP SIDE OF
 (PCB) BL0807N1006F PLUGSIN INTO
 FBS08051006F AND WILL ACCEPT
 CUSTOMERS BGA CHIP. PCB SOLDERS
 ONTO 80 PIN QFP FOOTPRINT ON MOTHER
 BOARD.

CONTRACT NO.	ADAPTERS-PLUS WWW.ADAPT-PLUS.COM, PH 209-839-0200			
APPROVALS:	INTERPOSER ADAPTER, CONVERTS 80 BGA TO 80 QFP			
DRAWN BY: ANDREW MONTOYA	SIZE A	FSCM NO.	DWG NO. CA80BG1006-80QFP	REV A
CHECKED: MIKE OIDEM	SCALE: 2:1		DATE : 11/07/07	SHEET: 1 OF 1
ISSUED: ANDREW MONTOYA				